


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	ADG/17/10607	
<b>1.3 Title of PCN</b>	DPAK IGBT and IGBT+Diode Assembly Capacity Expansion - Tongfu Microelectronics (China)	
<b>1.4 Product Category</b>	IGBT	
<b>1.5 Issue date</b>	2017-12-07	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	ROBERTSON HEATHER
<b>2.1.2 Phone</b>	+1 8475853058
<b>2.1.3 Email</b>	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Maurizio GIUDICE
<b>2.1.2 Marketing Manager</b>	Anna MOTTESE
<b>2.1.3 Quality Manager</b>	Vincenzo MILITANO

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Materials	New direct material part number (same supplier, different supplier or new supplier), Lead frame base material	Tongfu Microelectronics (China)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Selected DPAK IGBTs were manufactured in Shenzhen (China)	Selected DPAK IGBTs will be manufactured also in Tongfu Microelectronics (China)
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	no impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Improve service to Customers
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	by "GF" as first digits of the trace code, internal code (Finished Good) and Q.A. number
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2017-12-04
<b>7.2 Intended start of delivery</b>	2018-03-11
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	10607 Rel07-17.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2017-12-07

**9. Attachments (additional documentations)**

10607 Public product.pdf  
10607 DPAK IGBT and IGBT+Diode Assembly Capacity Expansion - TFME.pdf  
10607 Rel07-17.pdf  
10607 Comparison.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STGD4M65DF2	
	STGD5H60DF	
497-4352-2-ND	STGD5NB120SZT4	
	STGD6M65DF2	
	STGD6NC60HDT4	
497-4111-2-ND	STGD7NC60HT4	



## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCN Title :** DPAK IGBT and IGBT+Diode Assembly Capacity Expansion - Tongfu Microelectronics (China)

**PCN Reference :** ADG/17/10607

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STGD5H60DF	STGD14NC60KT4	STGD4M65DF2
STGD7NB60ST4	STGD7NC60HT4	STGD5NB120SZT4
STGD10NC60HT4	STGD6M65DF2	STGD10NC60HDT4



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